

ชื่อ _____ รหัส _____

มหาวิทยาลัยสงขลานครินทร์
คณะวิศวกรรมศาสตร์

การสอบปลายภาค ประจำภาคการศึกษาที่ 1
วันที่ : 3 ตุลาคม 2547
วิชา : 240-333 Microcomputer interfacing and
Applications

ปีการศึกษา 2547
เวลา : 13.30-16.30
ห้อง : A201

คำสั่ง

- ข้อสอบมีทั้งหมด 9 ข้อ คะแนนเต็ม 40 คะแนน ให้นักศึกษาทำหมดทุกข้อ
- นำเอกสารหรือหนังสือเข้าห้องสอบได้
- นำเครื่องคิดเลขเข้าห้องสอบได้

คำแนะนำ

- อ่านข้อสอบและดูวงจรให้ละเอียด(โดยเฉพาะชนิดของอุปกรณ์ที่ใช้ในวงจร)ก่อนเริ่มทำข้อสอบ
- เขียนคำตอบให้ชัดเจนด้วยลายมือที่ได้ อ่านง่าย

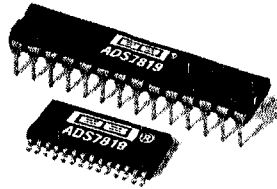
ทูลุจริตปรับโทษต่ำสุดปรับตักวิชานี้และพักการเรียน
1 ภาคการศึกษา โทษสูงสุดไล่ออก

- 1 นายสมชายซื้อมัลติมิเตอร์มาใช้งานตัวหนึ่ง นายสมชายพบว่ามัลติมิเตอร์ตัวนี้สามารถต่อกับพอร์ทอนุกรมได้ โดยรูปแบบต้องใช้เวลาในการรับส่ง 9600 bit/sec รูปแบบข้อมูล 7 บิต 1 stop bit และมีการตรวจสอบ even parity การส่งข้อมูลไปควบคุมมัลติมิเตอร์ต้องส่งไป 2 ไบต์ ไบต์แรกเป็นการส่งคำสั่งหลัก ไบต์สองเป็นการส่งคำสั่งย่อย ข้อมูลที่ส่งออกจากมัลติมิเตอร์ 1 ชุดมี 3 ไบต์ เป็นข้อมูลที่มัลติมิเตอร์วัดได้

จากคำอธิบายดังกล่าวจงตอบคำถามต่อไปนี้ (10 คะแนน)

- 1.1 นายสมชายต้องเขียนโปรแกรมกำหนดความเร็วในการรับส่ง 9600 bit/sec รูปแบบข้อมูล 7 บิต 1 stop bit และมีการตรวจสอบ even parity โดยใช้ภาษา C อย่างไรเมื่อนายสมชายต้องการใช้ com2 (4 คะแนน)

- 1.2 นายสมชายต้องเขียนโปรแกรมส่งข้อมูล โดยใช้ภาษา C อย่างไร ? (3 คะแนน)



ADS7819

12-Bit 800kHz Sampling CMOS ANALOG-to-DIGITAL CONVERTER

FEATURES

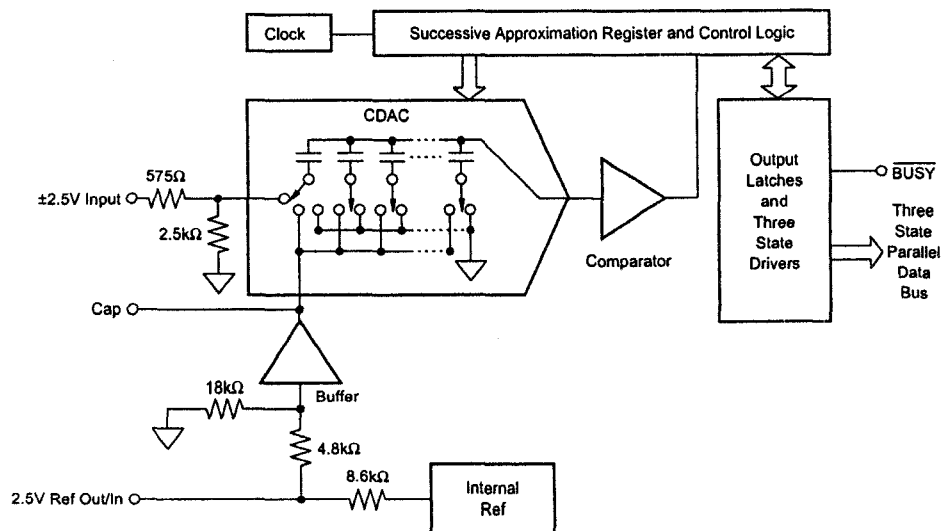
- 1.25 μ s THROUGHPUT TIME
- STANDARD ± 2.5 V INPUT RANGE
- 70dB min SINAD WITH 250kHz INPUT
- $\pm 3/4$ LSB max INL AND ± 1 LSB max DNL
- INTERNAL REFERENCE
- COMPLETE WITH S/H, REF, CLOCK, ETC.
- PARALLEL DATA w/ LATCHES
- 28-PIN 0.3" PDIP AND SOIC

DESCRIPTION

The ADS7819 is a complete 12-bit sampling A/D using state-of-the-art CMOS structures. It contains a complete 12-bit capacitor-based SAR A/D with inherent S/H, reference, clock, interface for microprocessor use, and three-state output drivers.

The ADS7819 is specified at an 800kHz sampling rate, and guaranteed over the full temperature range. Laser-trimmed scaling resistors provide a ± 2.5 V input range and inherent overvoltage protection up to ± 25 V.

The 28-pin ADS7819 is available in a plastic 0.3" DIP and in an SOIC, both fully specified for operation over the industrial -40°C to $+85^{\circ}\text{C}$ range.

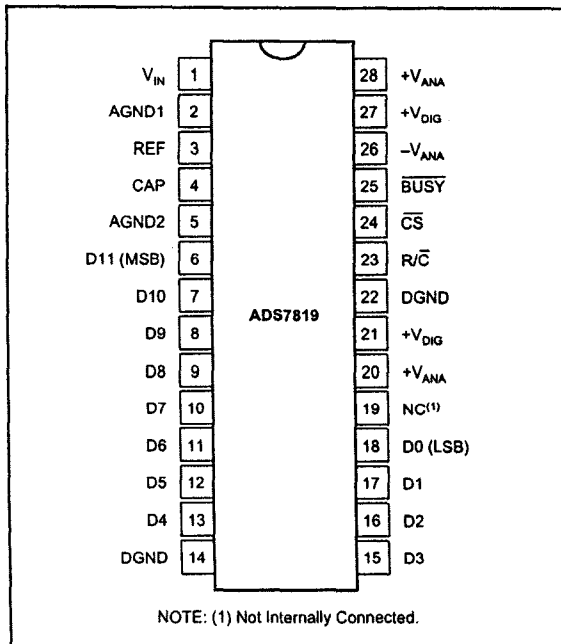


International Airport Industrial Park • Mailing Address: PO Box 11400 • Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd. • Tucson, AZ 85706
Tel: (520) 746-1111 • Twx: 910-952-1111 • Cable: BBRRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

PIN ASSIGNMENTS

PIN #	NAME	DIGITAL I/O	DESCRIPTION
1	V _{IN}		Analog Input. Connect via 50Ω to analog input. Full-scale input range is ±2.5V.
2	AGND1		Analog Ground. Used internally as ground reference point. Minimal current flow.
3	REF		Reference Input/Output. Outputs internal reference of +2.5V nominal. Can also be driven by external system reference. In both cases, decouple to ground with a 0.1μF ceramic capacitor.
4	CAP		Reference Buffer Output. 10μF tantalum capacitor to ground. Nominally +2V.
5	AGND2		Analog Ground.
6	D11 (MSB)	O	Data Bit 11. Most Significant Bit (MSB) of conversion results. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
7	D10	O	Data Bit 10. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
8	D9	O	Data Bit 9. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
9	D8	O	Data Bit 8. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
10	D7	O	Data Bit 7. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
11	D6	O	Data Bit 6. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
12	D5	O	Data Bit 5. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
13	D4	O	Data Bit 4. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
14	DGND		Digital Ground.
15	D3	O	Data Bit 3. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
16	D2	O	Data Bit 2. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
17	D1	O	Data Bit 1. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
18	D0 (LSB)	O	Data Bit 0. Least Significant Bit (LSB) of conversion results. Hi-Z state when \overline{CS} is HIGH, or when R/\overline{C} is LOW, or when a conversion is in progress.
19			Not internally connected.
20	+V _{ANA}		Analog Positive Supply Input. Nominally +5V. Connect directly to pins 21, 27 and 28.
21	+V _{DIG}		Digital Supply Input. Nominally +5V. Connect directly to pins 20, 27 and 28.
22	DGND		Digital ground.
23	R/ \overline{C}	I	Read/Convert Input. With \overline{CS} LOW, a falling edge on R/\overline{C} puts the internal sample/hold into the hold state and starts a conversion. With \overline{CS} LOW and no conversion in progress, a rising edge on R/\overline{C} enables the output data bits.
24	\overline{CS}	I	Chip Select. With R/\overline{C} LOW, a falling edge on \overline{CS} will initiate a conversion. With R/\overline{C} HIGH and no conversion in progress, a falling edge on \overline{CS} will enable the output data bits.
25	\overline{BUSY}	O	Busy Output. Falls when a conversion is started, and remains LOW until the conversion is completed and the data is latched into the output register. With \overline{CS} LOW and R/\overline{C} HIGH, output data will be valid when \overline{BUSY} rises, so that the rising edge can be used to latch the data.
26	-V _{ANA}		Analog Negative Supply Input. Nominally -5V. Decouple to ground with 0.1μF ceramic and 10μF tantalum capacitors.
27	+V _{DIG}		Digital Supply Input. Nominally +5V. Connect directly to pins 20, 21 and 28.
28	+V _{ANA}		Analog Positive Supply Input. Nominally +5V. Connect directly to pins 20, 21 and 27, and decouple to ground with 0.1μF ceramic and 10μF tantalum capacitors.

PIN CONFIGURATION



BASIC OPERATION

Figure 1 shows a basic circuit to operate the ADS7819. Taking $\overline{R/C}$ (pin 23) LOW for 40ns will initiate a conversion. \overline{BUSY} (pin 25) will go LOW and stay LOW until the conversion is completed and the output registers are updated. Data will be output in Binary Two's Complement with the MSB on D11 (pin 6). \overline{BUSY} going HIGH can be used to latch the data. All convert commands will be ignored while \overline{BUSY} is LOW.

\overline{CS}	$\overline{R/C}$	\overline{BUSY}	OPERATION
1	X	X	None. Databus in Hi-Z state.
↓	0	1	Initiates conversion. Databus remains in Hi-Z state.
0	↓	1	Initiates conversion. Databus enters Hi-Z state.
0	1	↑	Conversion completed. Valid data from the most recent conversion on the databus.
↓	1	1	Enables databus with valid data from the most recent conversion.
↓	1	0	Conversion in progress. Databus in Hi-Z state, enabled when the conversion is completed.
0	↑	0	Conversion in progress. Databus in Hi-Z state, enabled when the conversion is completed.
0	0	↑	Conversion completed. Valid data from the most recent conversion in the output register but the output pins D11-D0 are tri-stated.
X	X	0	New convert commands ignored. Conversion in progress.

Table I. Control Line Functions for 'read' and 'convert'.

The ADS7819 will begin tracking the input signal at the end of the conversion. Allowing 1.25 μ s between convert commands assures accurate acquisition of a new signal.

STARTING A CONVERSION

The combination of \overline{CS} (pin 24) and $\overline{R/C}$ (pin 23) LOW for a minimum of 40ns puts the sample/hold of the ADS7819 in the hold state and starts a conversion. \overline{BUSY} (pin 25) will go LOW and stay LOW until the conversion is completed and the internal output register has been updated. All new convert commands during \overline{BUSY} LOW will be ignored.

The ADS7819 will begin tracking the input signal at the end of the conversion. Allowing 1.25 μ s between convert commands assures accurate acquisition of a new signal. Refer to Table I for a summary of \overline{CS} , $\overline{R/C}$, and \overline{BUSY} states and Figures 2 and 3 for timing parameters.

DESCRIPTION	ANALOG VALUE	DIGITAL OUTPUT	
Full Scale Range	$\pm 2.5V$	BINARY TWO'S COMPLEMENT	
Least Significant Bit (LSB)	1.22mV	BINARY CODE	HEX CODE
+Full Scale (2.5V - 1LSB)	2.499V	0111 1111 1111	7FF
Midscale	0V	0000 0000 0000	000
One LSB below Midscale	-1.22mV	1111 1111 1111	FFF
-Full Scale	-2.5V	1000 0000 0000	800

TABLE II. Ideal Input Voltages and Output Codes.

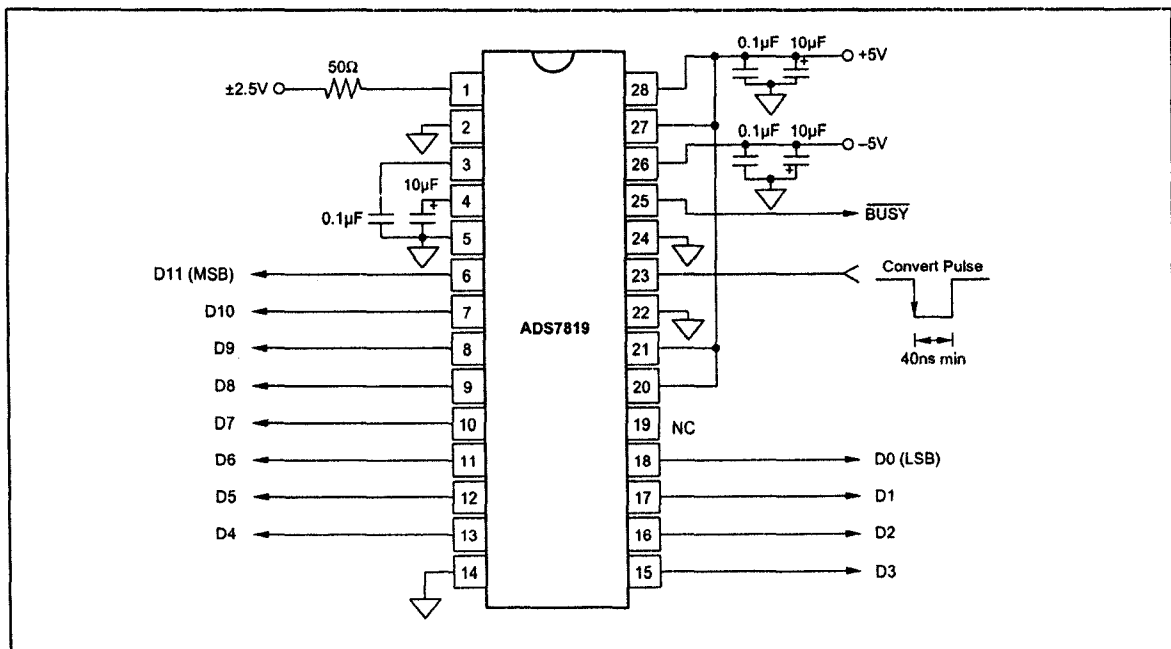


FIGURE 1. Basic Operation

\overline{CS} and R/\overline{C} are internally OR'd and level triggered. There is not a requirement which input goes LOW first when initiating a conversion. If it is critical that \overline{CS} or R/\overline{C} initiate the conversion, be sure the less critical input is LOW at least 10ns prior to the initiating input.

To reduce the number of control pins, \overline{CS} can be tied LOW using R/\overline{C} to control the read and convert modes. Note that the parallel output will be active whenever R/\overline{C} is HIGH and no conversion is in progress. See the **Reading Data** section and refer to Table I for control line functions for 'read' and 'convert' modes.

READING DATA

The ADS7819 outputs full parallel data in Binary Two's Complement data format. The parallel output will be active when R/\overline{C} (pin 23) is HIGH, \overline{CS} (pin 24) is LOW, and no conversion is in progress. Any other combination will tri-state the parallel output. Valid conversion data can be read in a full parallel, 12-bit word on D11-D0 (pins 6-13 and 15-18). Refer to Table II for ideal output codes.

After the conversion is completed and the output registers have been updated, \overline{BUSY} (pin 25) will go HIGH. Valid data from the most recent conversion will be available on D11-D0 (pins 6-13 and 15-18). \overline{BUSY} going HIGH can be used to latch the data. Refer to Table III and Figures 2 and 3.

Note: For best performance, the external data bus connected to D11-D0 should not be active during a conversion. The switching noise of the external asynchronous data signals can cause digital feed through degrading the converter's performance.

The number of control lines can be reduced by tying \overline{CS} LOW while using R/\overline{C} to initiate conversions and activate the output mode of the converter. See Figure 2.

INPUT RANGES

The ADS7819 has a $\pm 2.5V$ input range. Figures 4a and 4b show the necessary circuit connections for the ADS7819 with and without external hardware trim. Offset and full scale error⁽¹⁾ specifications are tested and guaranteed with the 50 Ω resistor shown in Figure 4b. This external resistor makes it possible to trim the offset $\pm 12mV$ using a trim pot or trim DAC. This resistor may be left out if the offset and gain errors will be corrected in software or if they are negligible in regards to the particular application. See the **Calibration** section of the data sheet for details.

The nominal input impedance of 3.125k Ω results from the combination of the internal resistor network shown on the front page of the product data sheet and the external 50 Ω resistor. The input resistor divider network provides inherent over-voltage protection guaranteed to at least $\pm 25V$. The 50 Ω , 1% resistor does not compromise the accuracy or drift of the converter. It has little influence relative to the internal resistors, and tighter tolerances are not required.

Note: The values shown for the internal resistors are for reference only. The exact values can vary by $\pm 30\%$. This is true of all resistors internal to the ADS7819. Each resistive divider is trimmed so that the proper division is achieved.

NOTE: (1) Full scale error includes offset and gain errors and is measured at both +FS and -FS.

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t_1	Convert Pulse Width	40			ns
t_2	Data Valid Delay After Start of Conversion		965	1100	ns
t_3	\overline{BUSY} Delay From Start of Conversion		70	125	ns
t_4	\overline{BUSY} LOW		960	1085	ns
t_5	\overline{BUSY} Delay After End of Conversion		90		ns
t_6	Aperture Delay		20		ns
t_7	Conversion Time		940	1030	ns
t_8	Acquisition Time		180	220	ns
t_7 & t_8	Throughput Time		1120	1250	ns
t_9	Bus Relinquish Time	10	50	83	ns
t_{10}	\overline{BUSY} Delay After Data Valid	20	65	100	ns
t_{11}	R/\overline{C} to \overline{CS} Setup Time	10			ns
t_{12}	Time Between Conversions	1250			ns
t_{13}	Bus Access Time	10	30	62	ns

TABLE III. Timing Specifications (T_{MIN} to T_{MAX}).

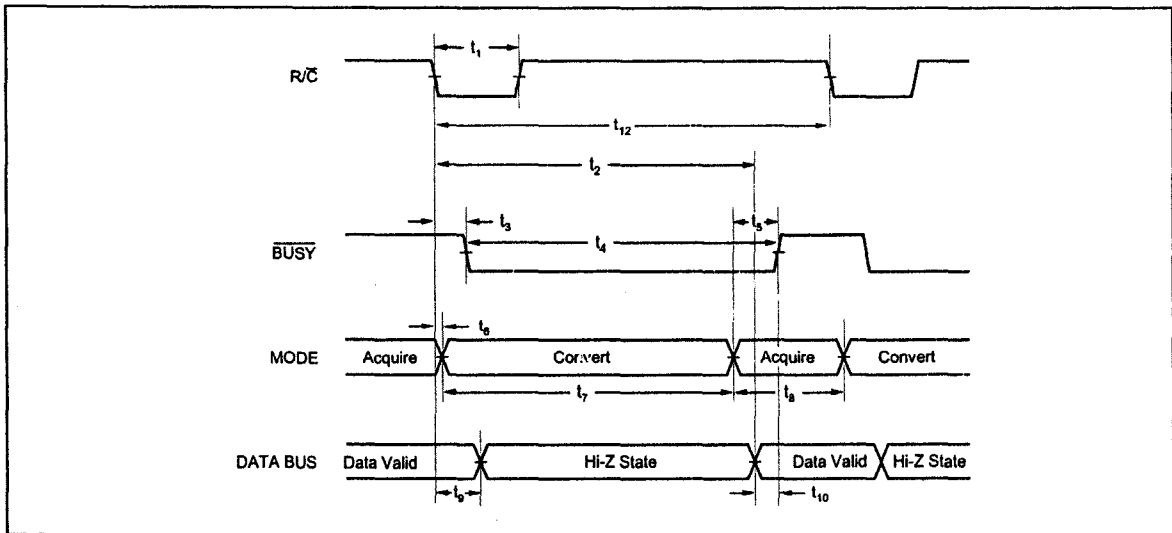


FIGURE 2. Conversion Timing with Outputs Enabled After Conversion (\overline{CS} Tied Low).

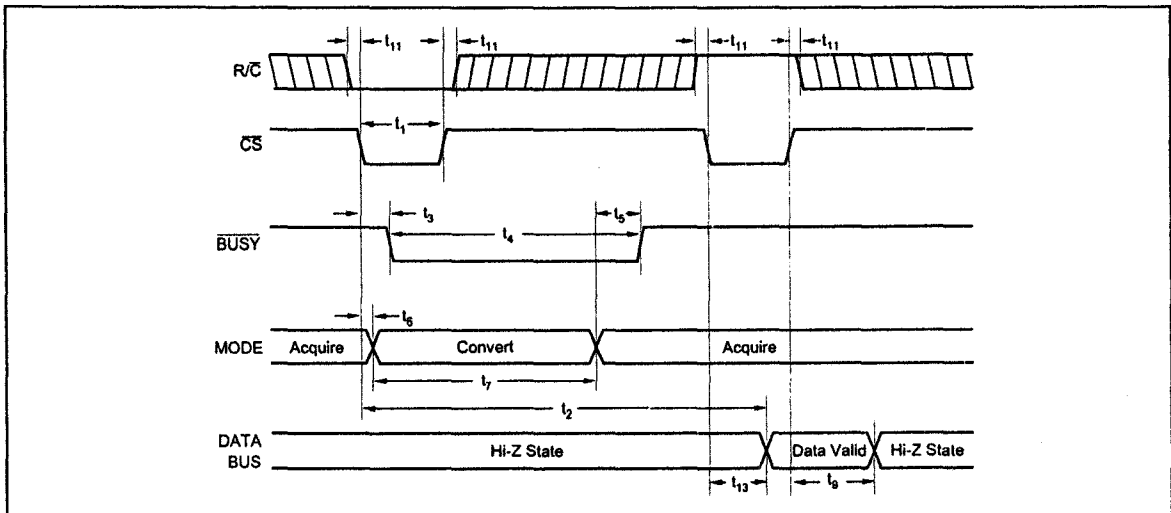


FIGURE 3. Using \overline{CS} to Control Conversion and Read Timing.

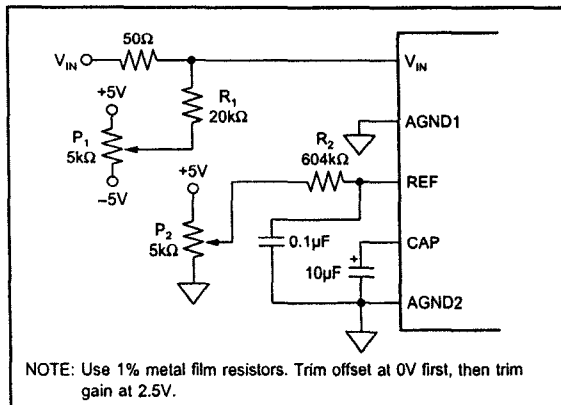


FIGURE 4a. Circuit Diagram With External Hardware Trim.

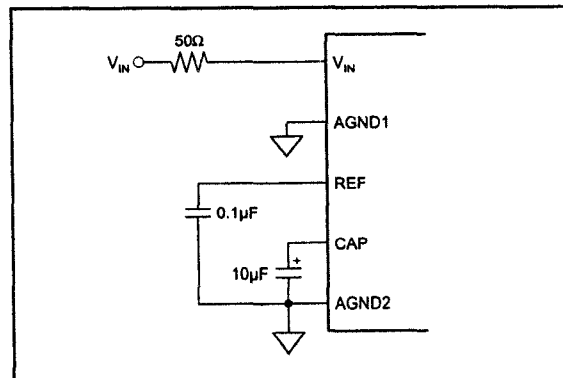
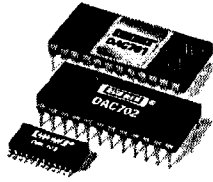


FIGURE 4b. Circuit Diagram Without External Hardware Trim.



**DAC701
DAC702
DAC703**

Monolithic 16-Bit DIGITAL-TO-ANALOG CONVERTERS

FEATURES

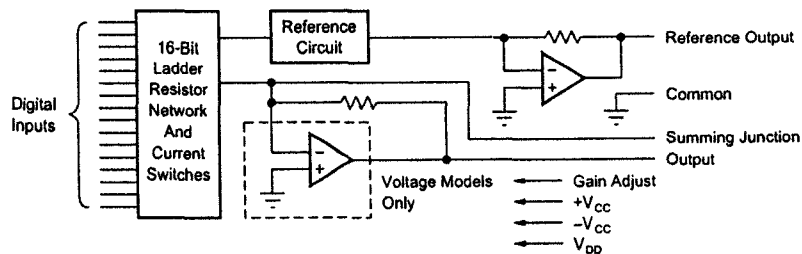
- **V_{OUT} AND I_{OUT} MODELS**
- **HIGH ACCURACY:**
Linearity Error $\pm 0.0015\%$ of FSR max
Differential Linearity Error $\pm 0.003\%$ of FSR max
- **MONOTONIC (at 15 bits) OVER FULL SPECIFICATION TEMPERATURE RANGE**
- **PIN-COMPATIBLE WITH DAC70, DAC71, DAC72**
- **DUAL-IN-LINE PLASTIC AND HERMETIC CERAMIC AND SOIC**

DESCRIPTION

The DAC70X family comprise of complete 16-bit digital-to-analog converters that includes a precision buried-zener voltage reference and a low-noise, fast-settling output operational amplifier (voltage output models), all on one small monolithic chip. A combination of current-switch design techniques accomplishes not only 15-bit monotonicity over the entire specified temperature range, but also a maximum end-point linearity error of $\pm 0.0015\%$ of full-scale range. Total full-scale gain drift is limited to $\pm 10\text{ppm}/^\circ\text{C}$ maximum (LH and CH grades).

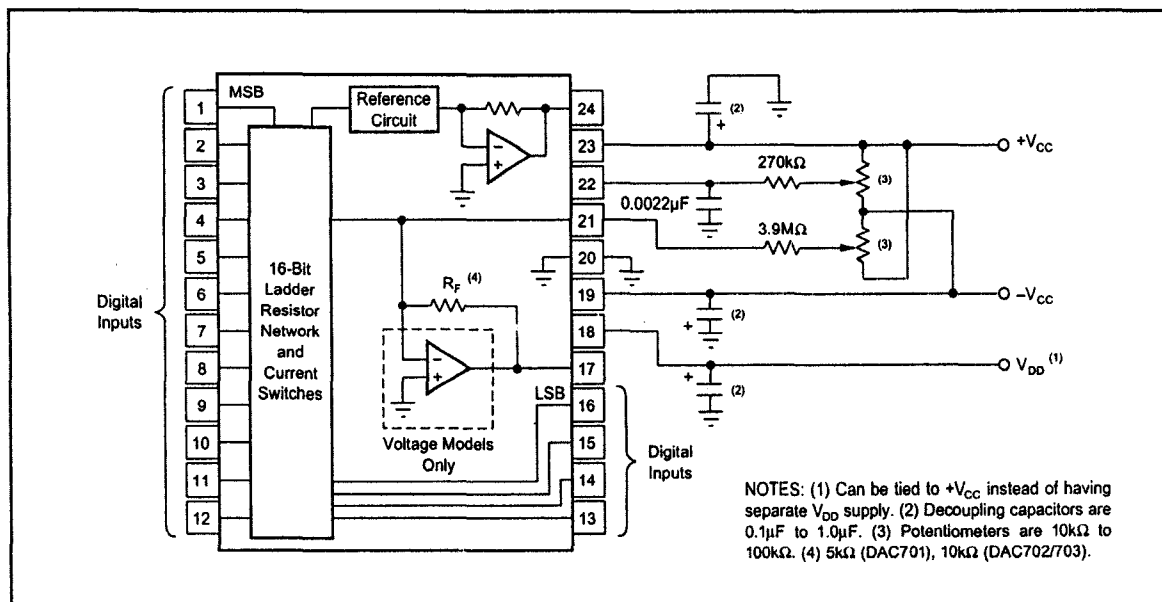
Digital inputs are complementary binary coded and are TTL-, LSTTL-, 54/74C- and 54/74HC-compatible over the entire temperature range. Outputs of 0 to +10V, $\pm 10\text{V}$, 0 to -2mA , and $\pm 1\text{mA}$ are available.

These D/A converters are packaged in hermetic 24-pin ceramic side-brazed or molded plastic. The DIP-packaged parts are pin-compatible with the voltage and current output DAC71 and DAC72 model families. The DAC702 is also pin-compatible with the DAC70 model family. In addition, the DAC703 is offered in a 24-pin SOIC package for surface mount applications.



International Airport Industrial Park • Mailing Address: PO Box 11400, Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd., Tucson, AZ 85706 • Tel: (520) 746-1111 • Twx: 910-952-1111
Internet: <http://www.burr-brown.com/> • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

CONNECTION DIAGRAMS



PIN ASSIGNMENTS

PIN #	ALL PACKAGES	
	DAC702	DAC701/703
1	Bit 1 (MSB)	Bit 1 (MSB)
2	Bit 2	Bit 2
3	Bit 3	Bit 3
4	Bit 4	Bit 4
5	Bit 5	Bit 5
6	Bit 6	Bit 6
7	Bit 7	Bit 7
8	Bit 8	Bit 8
9	Bit 9	Bit 9
10	Bit 10	Bit 10
11	Bit 11	Bit 11
12	Bit 12	Bit 12
13	Bit 13	Bit 13
14	Bit 14	Bit 14
15	Bit 15	Bit 15
16	Bit 16 (LSB)	Bit 16 (LSB)
17	$R_{FEEDBACK}$	V_{OUT}
18	V_{DD}	V_{DD}
19	$-V_{CC}$	$-V_{CC}$
20	Common	Common
21	I_{OUT}	Summing Junction (Zero Adjust)
22	Gain Adjust	Gain Adjust
23	$+V_{CC}$	$+V_{CC}$
24	+6.3V Reference Output	+6.3V Reference Output

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

$+V_{CC}$ to Common	0V, +18V
$-V_{CC}$ to Common	0V, -18V
V_{DD} to Common	0V, +18V
Digital Data Inputs to Common	-1V, +18V
Reference Out to Common	Indefinite Short to Common
External Voltage Applied to R_f (DAC702)	$\pm 18V$
External Voltage Applied to D/A Output (DAC701/703)	-5V to +5V
V_{OUT} (DAC701/703)	Indefinite Short to Common
Power Dissipation	1W
Storage Temperature	-60°C to +150°C
Lead Temperature (soldering, 10s)	300°C

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.